



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION

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26 Jun 2008

SUBJECT: ON Semiconductor Final Product/Process Change Notification # 16127

TITLE: Qualification of FlipChip International (FCI) for Flipchip Products

PROPOSED FIRST SHIP DATE: 26 Sep 2008

AFFECTED CHANGE CATEGORY(S): Subcontractor Assembly Site

AFFECTED PRODUCT DIVISION(S): DCG

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or Angela Tam <Angela.Tam@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available upon request

Contact your local ON Semiconductor Sales Office or Laura Rivers <laura.rivers@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This is a Final Product Change Notification announcing the qualification of FlipChip International (FCI) for the listed flipchip products. FCI currently manufactures other bump products for ON Semiconductor.

FCI is a fully certified ISO9001-2000 supplier. There will be no change in the wafer/die source therefore; no electrical performance or specifications will be changed.

This change is classified as a capacity expansion since the products listed below may be bumped at either FCI or the existing ASE qualified site once the final PCN expires.

**Final Product/Process Change Notification # 16127****RELIABILITY DATA SUMMARY:****Reliability Test Results:**

The qualification for FlipChip International (FCI) facility located in Phoenix, Arizona as an additional source for bump processing of micro-bump devices was previously qualified per FPCN# 15016, issued 14-Oct-2005; results as shown below. This FPCN is extending that qualification to additional devices in the same technology family, with additional Temp Cycle testing.

FCI Reliability Summary:

Temperature Cycle Tests (in all cases, TA=-40C to +125C, 500cycles):

Device Lot Result

1. NCP2890AFCT2G A 0/90
2. NCP2890AFCT2G B 0/90
3. NCP2890AFCT2G C 0/90
4. NCP2890AFCT2 A 0/90
5. NCP2890AFCT2 B 0/90
6. NUF4105FCT1 A 0/90
7. NUF6105FCT1 A 0/90
8. NUF6106FCT1 A 0/90

Ball Shear Tests (in-line monitoring):**Device Lot Result**

1. NCP2890AFCT2G A 0/5
2. NCP2890AFCT2 A 0/5
3. NUF4105FCT1 A 0/5
4. NUF6105FCT1 A 0/5
5. NUF6106FCT1 A 0/5

For Additional Products covered by this FPCN:

Temperature Cycle Tests (in all cases, TA=-40C to +125C, 500cycles):

Device Lot Result

1. NUF4105FCT1 A 0/90
2. NUF6105FCT1 A 0/90
3. NUF6106FCT1 A 0/90
4. NUF2441FCT1G A 0/80
5. NUF2441FCT1G B 0/80
6. NUF2441FCT1G C 0/80
7. NUF9001FCT1G A 0/80
8. NUF9001FCT1G B 0/80
9. NUF9001FCT1G C 0/80

ELECTRICAL CHARACTERISTIC SUMMARY:

N/A

CHANGED PART IDENTIFICATION:

Devices marked with date code 837 or later may be bumped at either qualified site (FCI or ASE)



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AFFECTED DEVICE LIST

NUF2222FCT1G
NUF2441FCT1G
NUF3101FCT1G
NUF4107FCT1G
NUF6105FCT1G
NUF6106FCT1G
NUF9001FCT1G
NUF9002FCT1G
NUP4103FCT1G